GS600SW Wafer-Level Dispensing Machine RDL First WLP CUF Application For Wafer Form Underfill

Our Product Introduction

Basic Information

Place of Origin:	China
Brand Name:	MingSeal
Certification:	ISO CE
Model Number:	GS600SW
Minimum Order Quantity:	1
Price:	$1000-$150000
Packaging Details:	WOODEN
Delivery Time:	5-60 days
Payment Terms:	L/C, T/T, D/A, D/P, MoneyGram, Western Union

Product Specification

Condition:	New
Voltage:	110V/220V
Automatic Grade:	Automatic
Warranty:	One Year
Highlight:	**Underfill Wafer-Level Dispensing Machine**, **GS600SW Wafer-Level Dispensing Machine**, **WLP CUF Wafer-Level Dispensing Machine**

for more products please visit us on mingseal-en.com

Product Description

SS101 Wafer-Level Dispensing Machine

For Wafer Form Underfill

SS101 is a highly stable and precise wafer level dispensing system which is developed based on Under fill process requirements of RDL First WLP.

The equipment meets the needs of the semiconductor industry,can be provided with an automatic wafer loading & unloading system , and can automatically realize functions such as wafer handling , alignment , preheating , operation heating and heat dissipation . It is compatible with international semiconductor communication protocols , and is provided with an AMHS automatic loading & unloading robot interface to match the information management requirements and unmanned management trends.

SS101 System Layout

① Loadport & Foup
② Aligner
③ QR code scanning station
④ Pre-heating station
⑤Heat dissipation station
⑥GS600SWA Dispensing Machine work station ⑦GS600SWB Dispensing Machine work station
⑧Robot Handling module

Composition of SS101 Wafer-Level Dispensing System

GS600SW wafer-level dispensing machine × 2
PC101 wafer loading & unloading machine × 1

Application Fields

RDL First WLP
CUF Application

SS101 Wafer-Level Dispensing Operation Flow

Features and Advantages

Supporting 8/12-inch wafer dispensing.

Dustproof level 10, meeting the environmental requirements of wafer level packaging.

ESD protection meeting international IEC and ANSI standards.

In the whole process of wafer turnover and operation, the temperature is finely controlled and automatically corrected to meet the CUF process requirements while ensuring the product safety.

The whole-process video monitoring facilitates product turnover, operation process observation, and problem tracing and analysis

Technical Specifications

SS101 system	GS600SWA * 1 ,GS600SWB * 1, PC101 Wafer Handling Machine * 1 (EFEM)	
Application Fields	RDL First WLP, CUFApplication	
Cleanliness Level	Cleanliness of working area	Class 100 (Class 1000 workshop) Class 10 (Class 100 workshop)
Product Application Fields	Support for wafer size	φ200mm±0 .5mm, φ300mm±0.5mm (Standard model supports 12-inch wafers only)
	Support for wafer thickness	300-2550μ m
	Allowable wafer max. warpage range	5mm (as per Robot Finger type)
	Allowable max.wafer weight	600g (as per Robot Finger type)
	Wafer cassette form	8 inches Open Cassette,12 inches Foup (Standard model supports 12-inch wafers only)
PC101(EFEM)	Loading&unloading method	Loadport+Robots
	Pre-Aligner accuracy	Round center correction deviation≤±0 . 1mm Angle correction deviation≤±0 .2 °
	Wafer reader	Supports SEMI fonts (Flat or concave/convex surfaces) ,non-SEMI fonts
	Preheating temp. range	Room temperature~180℃
	Wafer cooling method	Natural cooling or air cooling
	Transmission mechanisms	X/Y: Linear motor Z: Servo motor&Screw module

Dispensing Motion System	Repeatability	X/Y: ±3μ mZ: ±5μ m
	Positioning accuracy	X/Y: ±10μ m
	Max. movement speed	X/Y: 1000mm/s Z: 500mm/s
	Max. accelerated velocity	X/Y: 1g Z: 0 .5g
Vision System	Camera pixels	130W
	Recognition accuracy	±1 Pixel
	Recognition range	12 × 16mm Recognition range 19 .2 ×25 .6mm
	Light source	Combined three-color light source red, green, white + red
Weighing Calibration System	Weighing accuracy	0.01mg
Chuck Table Load Tray	Vacuum surface flatness deviation	≤ 3 0 um
	Heating temp.range	Room temperature~180℃
	Heating temp. deviation	≤ ± 1 . 5 ℃
	Repeatability of lifting height	±10 μ m
	Vacuum suction pressure	-70~-85Kpa Settable
Facilities	Footprint (W*D*H)	3075×2200×2200mm(Display unfolded)
	Weight	2.9t
	Power supply	200~240VAC,47~63HZ (Single-phase voltage adaptation power supply)
	Electric current	75A
	Power	16.5KW
	Inhale	(0.5Mpa, 450L/min) ×5 way
	Operating ambient temp.	23℃±3℃
	Relative humidity of working environment	30 ~ 70%